Abstract

The invention relates in particular to the separation and transportation of a disc shaped substrate (102; 202) such as e.g. a solar wafer.

The invention is characterized by the fact that separations take place within a fluid, and that adhesion forces resulting from a thin fluid film develop between a gripper (108; 208) and the substrate to be separated (102; 202) that enable adherance to the gripper (108; 208).

Through unloading perpendicular to the feed direction (105; 205) or particularly in parallel to the planar design of the substrates (102; 202), a very gentle and efficient separation of disc shaped substrates (102; 202) is possible with a short cycle time.

(Fig. 1A)